

推奨基板寸法
RECOMMENDED PCB PATTERN LAYOUT
(SCALE:2-1)

注記 NOTES

- 材質
MATERIAL
ハウジング : ガラス入り LCP、白色、UL94V-0
HOUSING: G.F.LCP, WHITE, UL94V-0
ターミナル : 銅合金 (t=0.2)
TERMINAL: COPPER ALLOY
ネイル : 銅合金 (t=0.25)
NAIL: COPPER ALLOY
- メッキ仕様
PLATING
ターミナル : 接点部 : 金メッキ 0.25 μm MIN.
TERMINAL : CONTACT AREA; GOLD 0.25 MICROMETER MIN.
半田付け部 : 錫メッキ 2.0 μm MIN.
SOLDER TAIL AREA; TIN 2.0 MICROMETER MIN.
下地メッキ : ニッケルメッキ 2.0 μm MIN.
UNDER-PLATING: NICKEL 2.0 MICROMETER MIN.
補強金具 : 錫メッキ 1.0 μm MIN.
FITTING NAIL : TIN 1.0 MICROMETER MINIMUM
下地メッキ : ニッケルメッキ 1.0 μm MIN.
UNDER-PLATING: NICKEL 1.0 MICROMETER MIN.

10 mm	53553 SERIES
9 mm	53552 SERIES
8 mm	53551 SERIES
7 mm	53481 SERIES
6 mm	53467 SERIES
5 mm	53475 SERIES
基板間寸法 STACKING HEIGHT	嵌合相手 TO BE MATED WITH

WITHOUT HSG LOCK	80.47	84.07	78.87	75.565	—	52760-2479	240
	67.77	71.37	66.17	62.865	—	52760-2079	200
	61.42	65.02	59.82	56.515	—	52760-1879	180
WITH HSG LOCK	55.07	58.67	53.47	50.165	—	52760-1679	160
	23.32	26.92	21.72	18.415	52760-0678	—	60
	20.15	23.75	18.55	15.24	52760-0578	52760-0579	50
D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	STICK PACKAGE オーダー番号 ORDER NO.	極数 CIRCUITS	

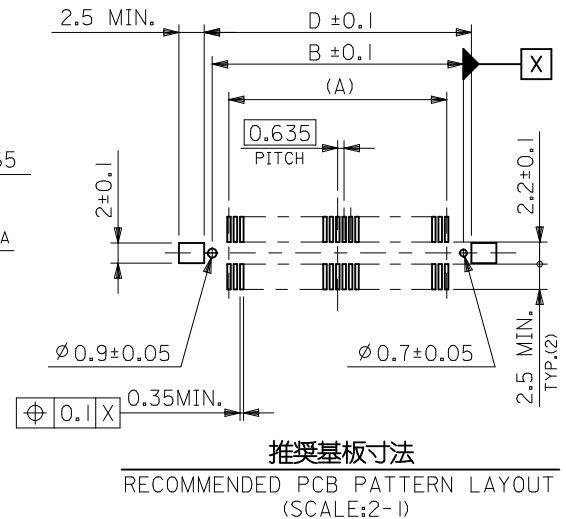
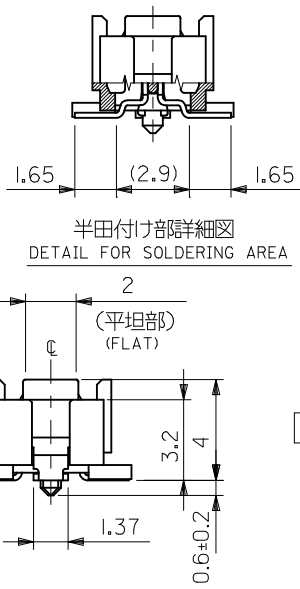
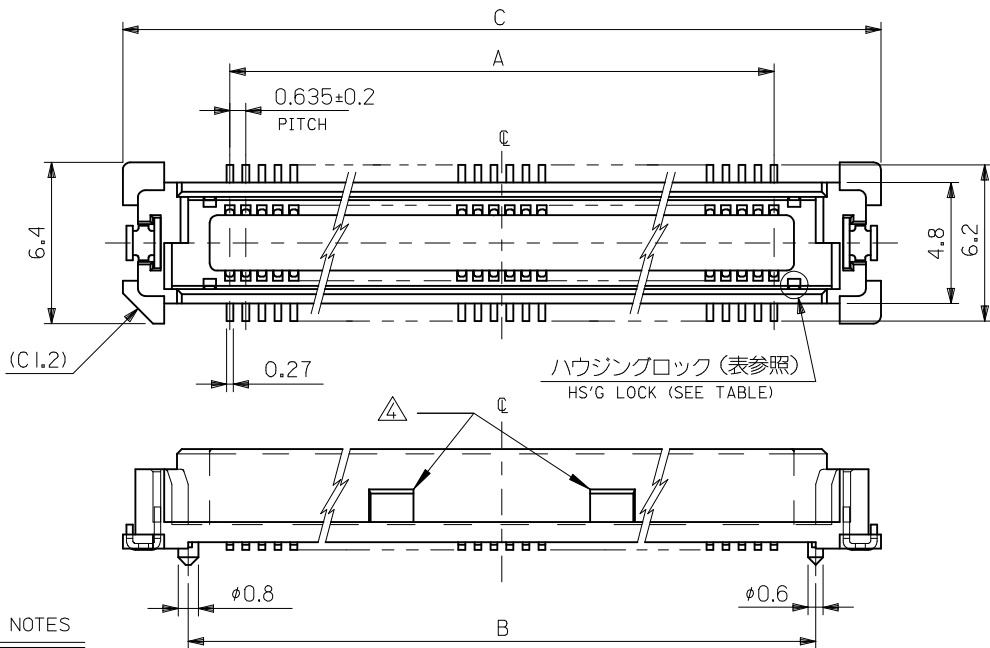
CONNECTOR SERIES No. : 52760-***70

- 200極以下のテール平坦度は 0.1 MAX.、
TAIL COPLANARITY TO BE 0.1 MAX.
240極のテール平坦度は 0.12 MAX.とする。
IN 240 CIRCUITS, TAIL COPLANARITY TO BE 0.12 MAX.

△ 本製品は 2016 年 6 月 30日まで形状変更期間中となります。
THIS PRODUCT IS DURING A FORM CHANGE PERIOD TILL JUNE 30, 2016.
その為、図示形状が無い場合もございますが、製品機械性能上問題ございません。
THEREFORE, THERE MAY NOT BE THE ILLUSTRATED SHAPE.
HOWEVER, IT DOES NOT AFFECT ON CONNECTOR MECHANICAL PERFORMANCE.

REVISED EC NO: J2017-0575 DRAWINGS CHKD: MSASAO APPR: MSASAO 2017/05/15 2017/06/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY Y. WADA	DATE '04/02/26	TITLE 0.635 PITCH B-TO-B S/T REC. HSG ASSY -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY M. SASAO	DATE '04/02/26		
	0.5 OVER	1.0 UNDER	±0.1	APPROVED BY M. SASAO	DATE '04/02/26		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
10 OVER	30 UNDER	±0.25	SEE CHART		SD-52760-013		1 OF 1
30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR ±3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

10 9 8 7 6 5 4 3 2 1



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10 OVER	30 UNDER	±0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SD-52760-013		
ANGULAR	±3 °				1 OF 1		

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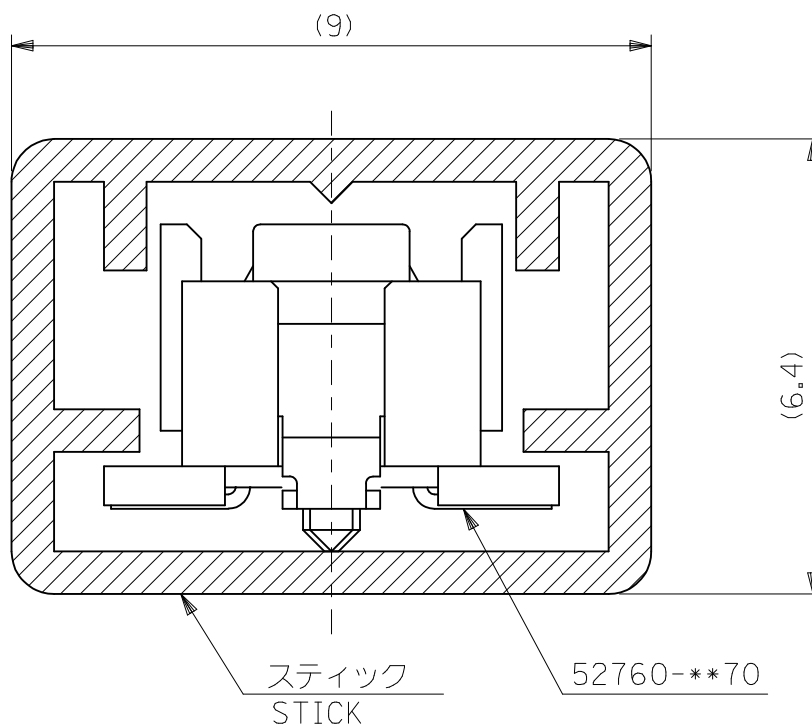
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注)
NOTES.

- スティック両端はキャップ止め。
BOTH ENDS WITH CAPS.
- 全長： 600±2
TOTAL LENGTH
- 肉厚：0.6±0.2
THICKNESS
- 量産対応済の極数については、
SD-52760-013を参照下さい。
SEE SD-52760-013 FOR AVAIRABLE ITEMS.
- 本製品は52760-***9の鉛フリー品
である。
THIS PRODUCT IS LEAD FREE OF 52760-***9.



6	52760-2479	240
7	↑ -2079	200
8	↓ -1879	180
9	↓ -1679	160
23	52760-0579	50
梱包数 QUANTITY	MATERIAL NO.	極数 NO. OF CKT.

REVISED EC NO: J2017-0575 DRWN:GES 2017/05/15 CHKD: APPR:MSASAO 2017/06/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	±	DRAWN BY Y.WADA	DATE 2004/02/26	TITLE 52760-***70 STICK PACKAGING -LEAD FREE-			
0.25 OVER 0.5 UNDER	±	CHECKED BY M.SASAO	DATE 2004/02/26	DOCUMENT NO. SD-52760-015				
0.5 OVER 1.0 UNDER	±	APPROVED BY M.SASAO	DATE 2004/02/26					
0 OVER 10 UNDER	±0.2	MATERIAL NO. SEE CHART		SHEET NO. 1 OF 1				
10 OVER 30 UNDER	±0.25	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS						
30 OVER	±0.3							
ANGULAR	±3 °	SIZE A4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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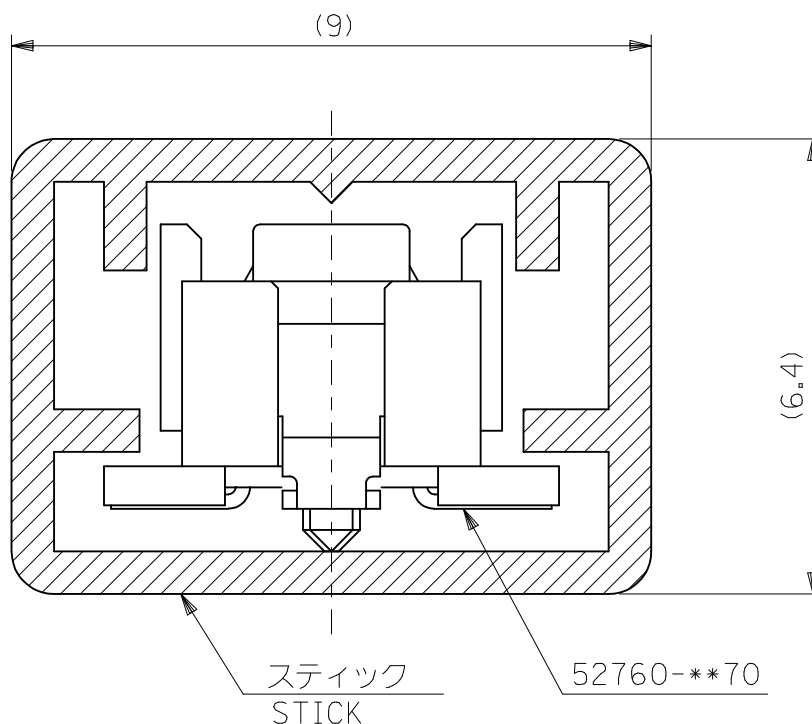
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0.25 OVER 0.5 UNDER	±	CHECKED BY M.SASAO	DATE 2004/02/26	DOCUMENT NO. SD-52760-015				
0.5 OVER 1.0 UNDER	±	APPROVED BY M.SASAO	DATE 2004/02/26					
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